# Getting Started Guide: BOOST-ADS7042

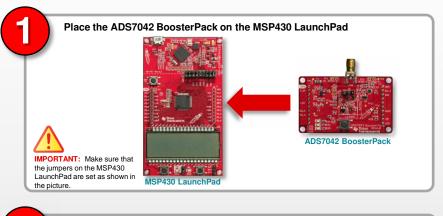


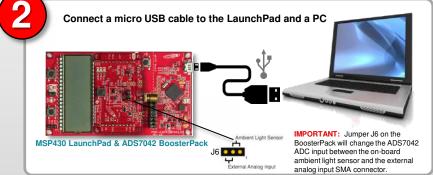
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The ADS7042 Ultra-Low Power Data Acquisition BoosterPack is ideal for evaluating and starting development with the ADS7042 precision analog to digital converter (ADC). The ADS7042 BoosterPack is compatible with the TI LaunchPad<sup>™</sup> ecosystem. Demonstration software for the BoosterPack is available for the MSP430FR4133 microcontroller LaunchPad. The BoosterPack can also be used with other host processors via the SPI interface pins on the top of the board.



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#### Run the software



Load and run the Energia Sketch demo software by clicking on the green 'Run' button.

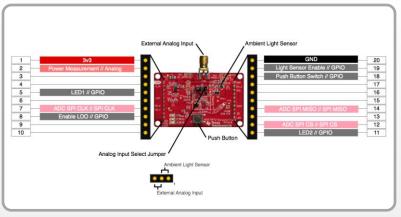
- The LCD on the MSP430 LaunchPad will display an introduction message followed by the measured power consumption of the ADC and voltage reference on the BoosterPack.
- The ADC sampling rate can be changed by pressing Switch S1 and S2 on the Launchpad.
- Switch S1 on the BoosterPack changes the display from power consumption to raw hex conversion data. This data is also transmitted to the PC on the USB cable via a virtual COM port.
  NOTE: JP1 on the LaunchPad may have to be removed to enable this feature.





TI E2E community Technical support for TI Precision ADCs can be found at http://www.ti.com/precisionadcsupport

### **BOOST-ADS7042 BoosterPack**



More information about Precision Analog SAR ADCs can be found at http://www.ti.com/precisionadc

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